



SOT1910-1

LFLGA54, plastic low profile, fine pitch, land grid array package; 54 terminals; 0.5 mm pitch; 6 mm x 9.7 mm x 1.17 mm body

25 September 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFLGA54
Package style descriptive code	FLGA (fine-pitch land grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-01-2017
Manufacturer package code	SOT1910

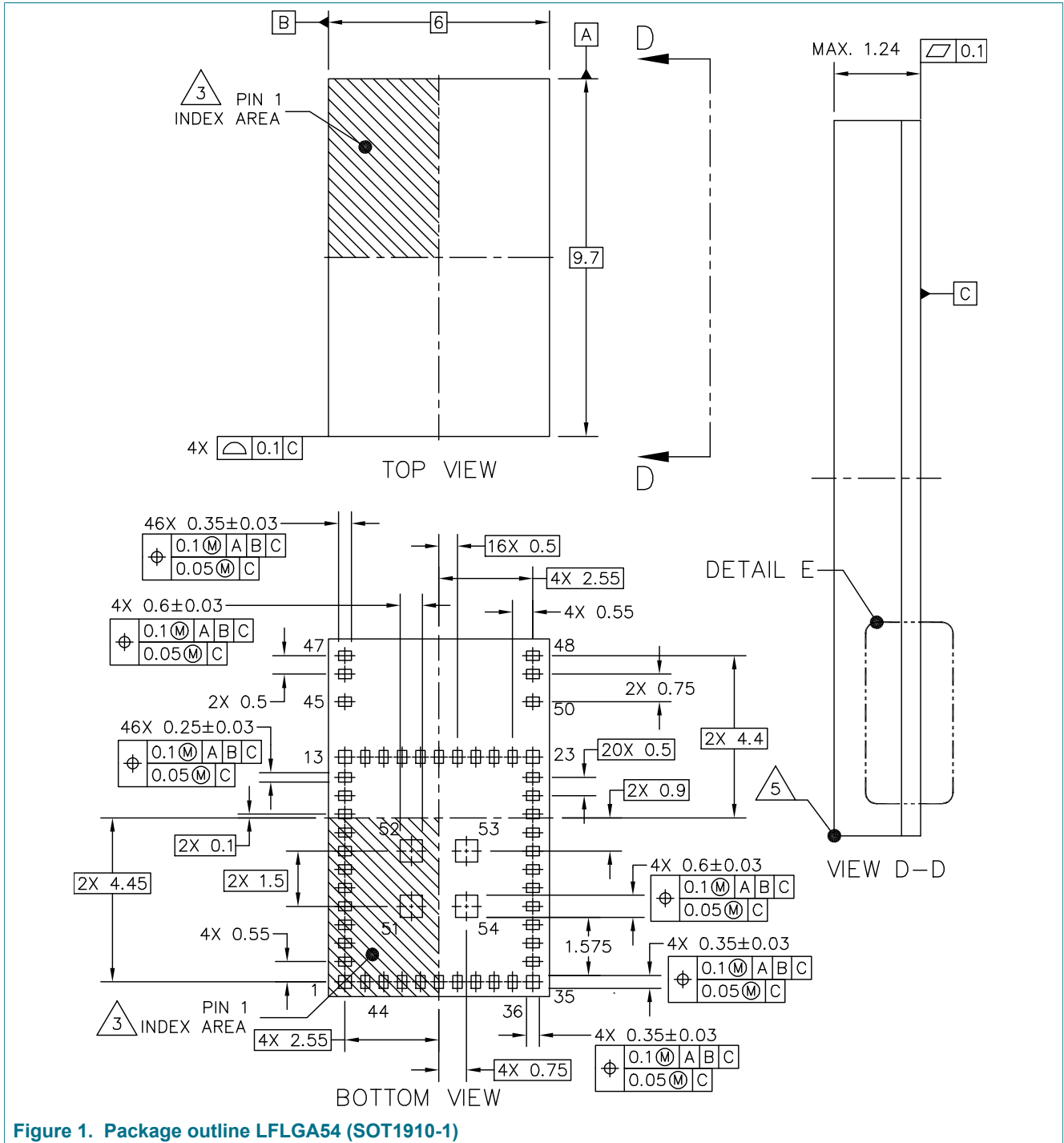
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	9.7	-	mm
seated height	-	1.17	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	54	-	

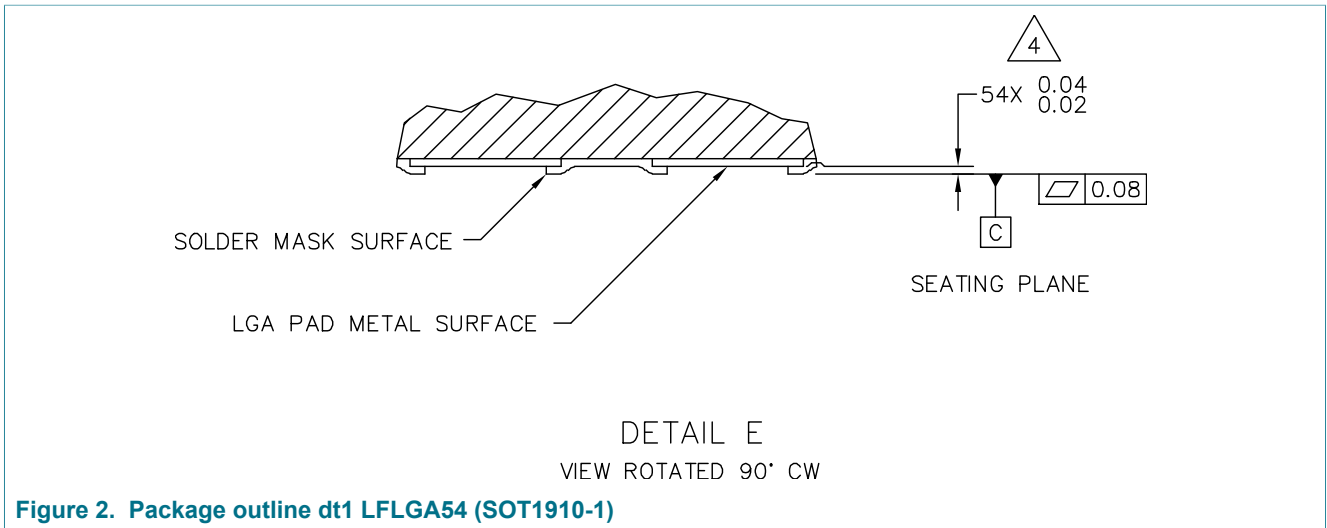


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2 Package outline



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.



PIN 1 CONFIGURATION MAY VARY.



DIMENSION APPLIES TO ALL LEADS.



SIDE WALL SPUTTER 1~3um; TOP SURFACE SPUTTER 3~6um

Figure 3. Package outline note LFLGA54 (SOT1910-1)

3 Legal information

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